



Material Content Data Sheet



Sales Product Name		2EDL23I06PJ		Issued		29. August 2013		
MA#		MA001140334						
Package		PG-DSO-14-49		Weight*		139.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.871	1.34	1.34	13450	13450
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		413	
	non noble metal	iron	7439-89-6	1.150	0.83		8265	
wire	non noble metal	copper	7440-50-8	46.675	33.56	34.44	335588	344369
	noble metal	gold	7440-57-5	0.258	0.19	0.19	1856	1856
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1247
	plastics	epoxy resin	-	9.368	6.74		67358	
	inorganic material	silicondioxide	60676-86-0	77.202	55.51	62.37	555078	623683
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8816	8816
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2204	2204
glue	plastics	acrylic resin	-	0.172	0.12		1237	
	noble metal	silver	7440-22-4	0.610	0.44	0.56	4385	5622
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com